



# PMEG2020CPA

20 V, 2 A low VF dual Schottky barrier rectifier

10 September 2024

Product data sheet

## 1. General description

Planar Schottky barrier rectifier in common cathode configuration with an integrated guard ring for stress protection, encapsulated in a SOT1061 leadless small Surface-Mounted Device (SMD) plastic package with medium power capability.

## 2. Features and benefits

- Average forward current  $I_{F(AV)} \leq 2$  A
- Reverse voltage  $V_R \leq 20$  V
- Low forward voltage
- Exposed heat sink (cathode pad) for excellent thermal and electrical conductivity
- Leadless small SMD plastic package with medium power capability
- AEC-Q101 qualified

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption application
- Battery chargers for mobile equipment

## 4. Quick reference data

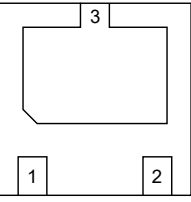
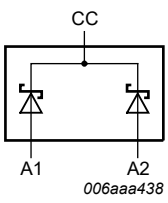
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per diode</b>						
$I_{F(AV)}$	average forward current	square-wave pulse; $\delta = 0.5$ ; $f = 20$ kHz; $T_{amb} \leq 80$ °C	[1]	-	2	A
		square-wave pulse; $\delta = 0.5$ ; $f = 20$ kHz; $T_{amb} \leq 140$ °C		-	2	A
$V_R$	reverse voltage	$T_j \leq 25$ °C	-	-	20	V
$V_F$	forward voltage	$I_F = 2$ A; $T_j = 25$ °C	-	385	420	mV
$I_R$	reverse current	$V_R = 20$ V; $T_j = 25$ °C	-	380	1000	$\mu$ A

[1] Device mounted on a ceramic PCB,  $Al_2O_3$ , standard footprint.

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode (diode 1)	 <p>Transparent top view DFN2020-3 (SOT1061)</p>	 <p>006aaa438</p>
2	A2	anode (diode 2)		
3	CC	common cathode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
<a href="#">PMEG2020CPA</a>	DFN2020-3	plastic, leadless thermal enhanced ultra thin small outline package; 3 terminals; 1.3 mm pitch; 2 mm x 2 mm x 0.65 mm body	<a href="#">SOT1061</a>

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG2020CPA	AL

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
<b>Per diode</b>						
$V_R$	reverse voltage	$T_j \leq 25\text{ }^\circ\text{C}$		-	20	V
$I_{F(AV)}$	average forward current	square-wave pulse; $\delta = 0.5$ ; $f = 20\text{ kHz}$ ; $T_{amb} \leq 80\text{ }^\circ\text{C}$	[1]	-	2	A
		square-wave pulse; $\delta = 0.5$ ; $f = 20\text{ kHz}$ ; $T_{amb} \leq 140\text{ }^\circ\text{C}$		-	2	A
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1\text{ ms}$ ; $\delta \leq 0.25$		-	7	A
$I_{FSM}$	non-repetitive peak forward current	square-wave pulse; $t_p = 8\text{ ms}$ ; $T_{j(init)} = 25\text{ }^\circ\text{C}$		-	9	A
<b>Per device, one diode loaded</b>						
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ }^\circ\text{C}$	[2] [3]	-	500	mW
			[2] [4]	-	960	mW
			[1] [2]	-	1.8	W
$T_j$	junction temperature			-	150	$^\circ\text{C}$

Symbol	Parameter	Conditions	Min	Max	Unit
$T_{amb}$	ambient temperature		-55	150	°C
$T_{stg}$	storage temperature		-65	150	°C

- [1] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [2] Reflow soldering is the only recommended soldering method.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2] [3]	-	-	250	K/W
			[1] [2] [4]	-	-	130	K/W
			[1] [2] [5]	-	-	70	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[6]	-	-	12	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.
- [2] Reflow soldering is the only recommended soldering method.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [5] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [6] Soldering point of cathode tab.

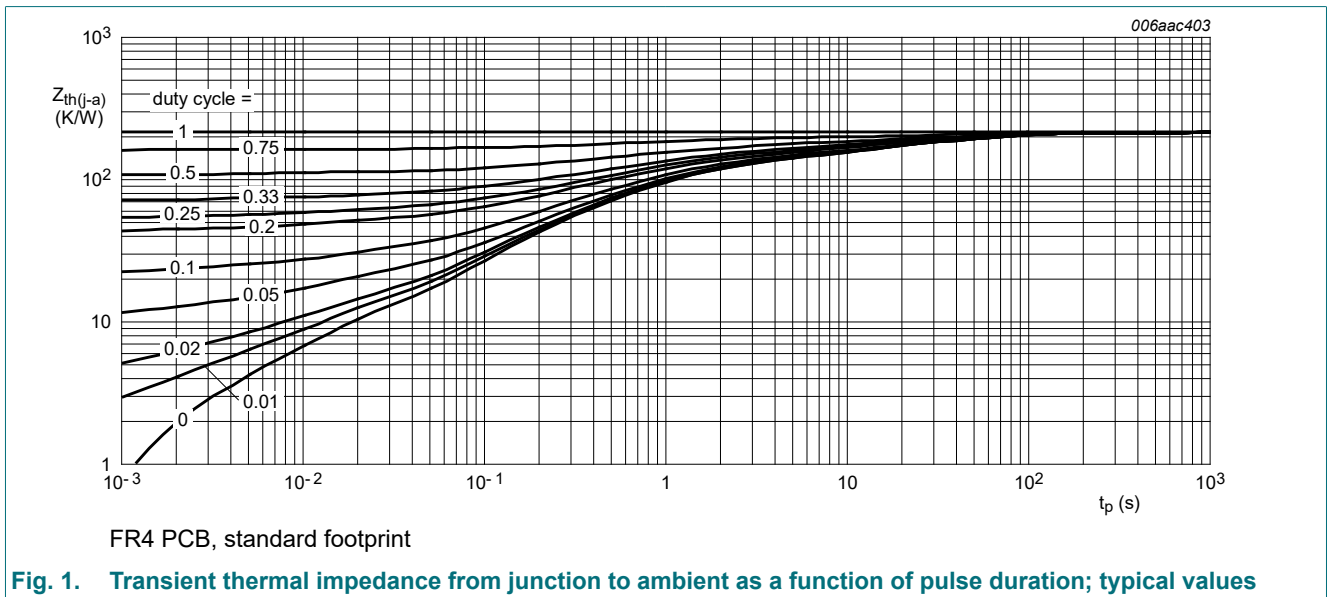


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

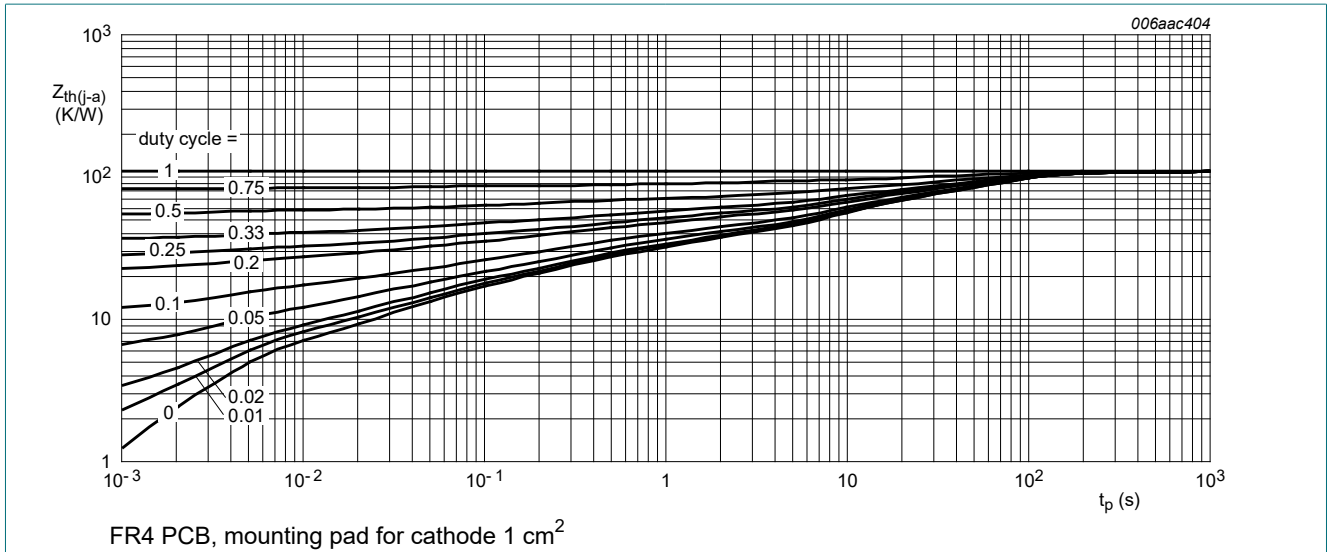


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

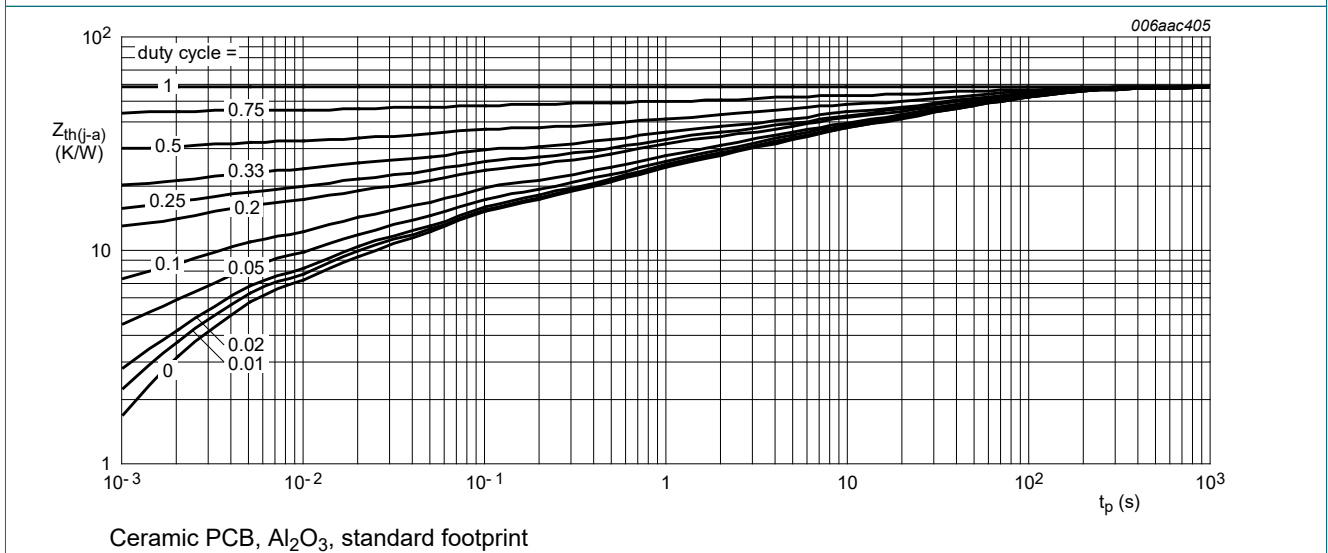


Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per diode</b>						
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 100 mA; T <sub>j</sub> = 25 °C	-	220	-	mV
		I <sub>F</sub> = 1 A; T <sub>j</sub> = 25 °C	-	320	360	mV
		I <sub>F</sub> = 2 A; T <sub>j</sub> = 25 °C	-	385	420	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 10 V; T <sub>j</sub> = 25 °C	-	160	-	μA
		V <sub>R</sub> = 20 V; T <sub>j</sub> = 25 °C	-	380	1000	μA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C	-	175	-	pF
		V <sub>R</sub> = 10 V; f = 1 MHz; T <sub>j</sub> = 25 °C	-	65	-	pF
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 10 mA; I <sub>R</sub> = 10 mA; I <sub>R(meas)</sub> = 1 mA; R <sub>L</sub> = 100 Ω; T <sub>j</sub> = 25 °C	-	-	55	ns

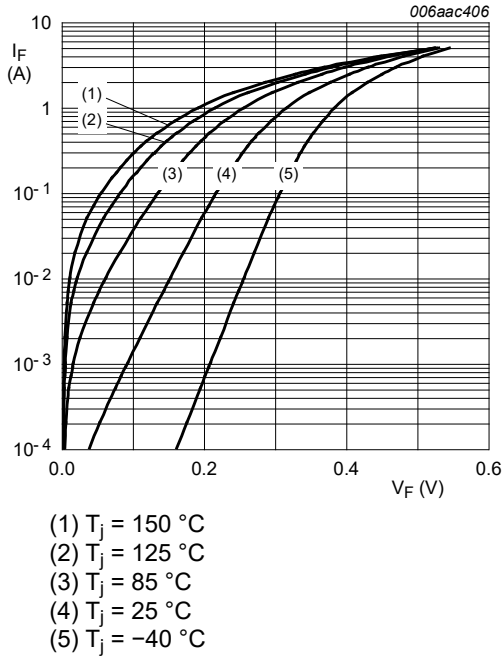


Fig. 4. Forward current as a function of forward voltage; typical values

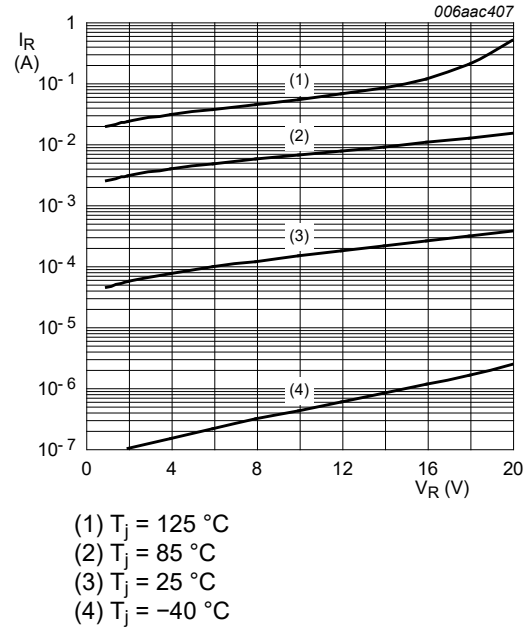


Fig. 5. Reverse current as a function of reverse voltage; typical values

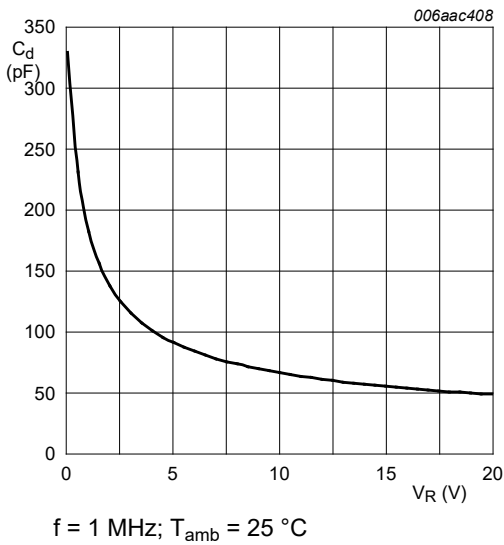


Fig. 6. Diode capacitance as a function of reverse voltage; typical values

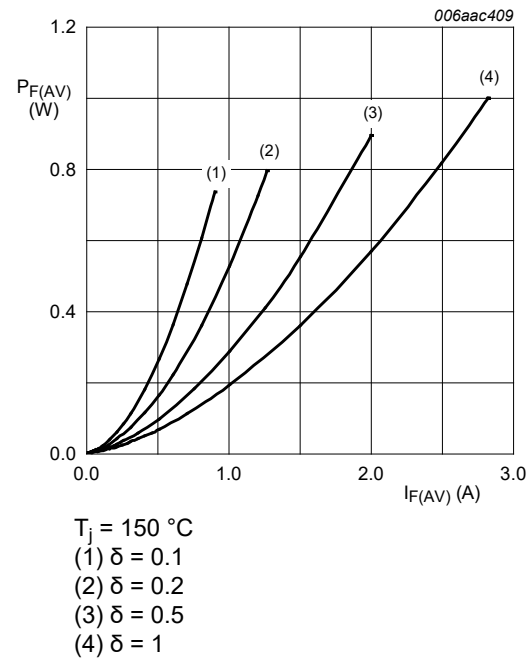
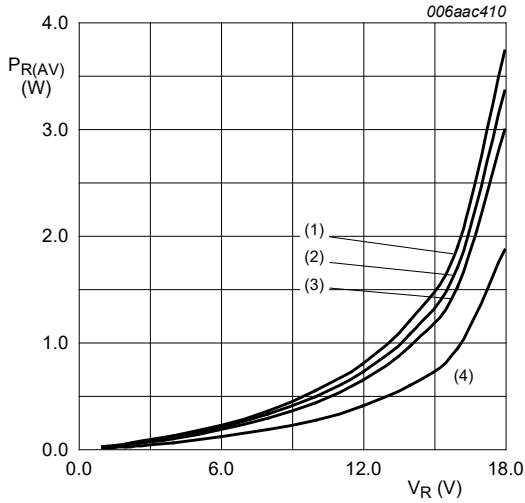
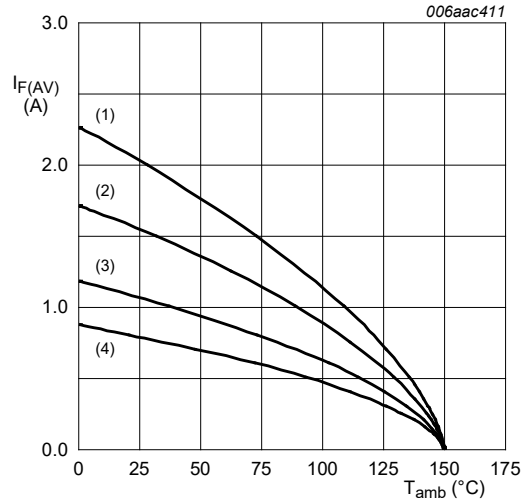


Fig. 7. Average forward power dissipation as a function of average forward current; typical values



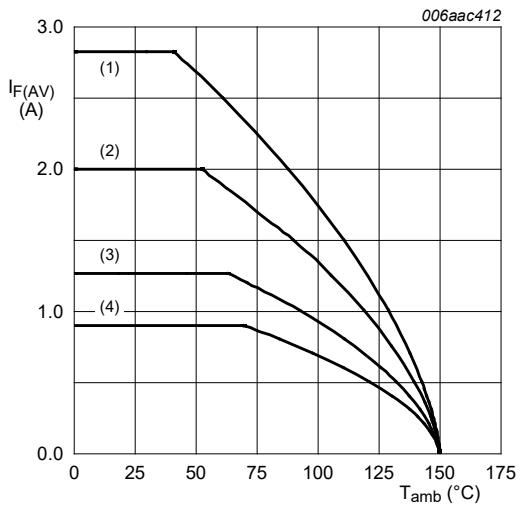
$T_j = 125\text{ }^\circ\text{C}$   
 (1)  $\delta = 1$   
 (2)  $\delta = 0.9$   
 (3)  $\delta = 0.8$   
 (4)  $\delta = 0.5$

**Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values**



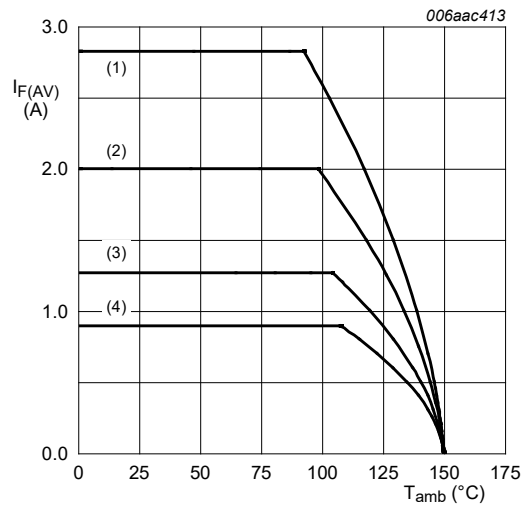
FR4 PCB, standard footprint  
 $T_j = 150\text{ }^\circ\text{C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 9. Average forward current as a function of ambient temperature; typical values**



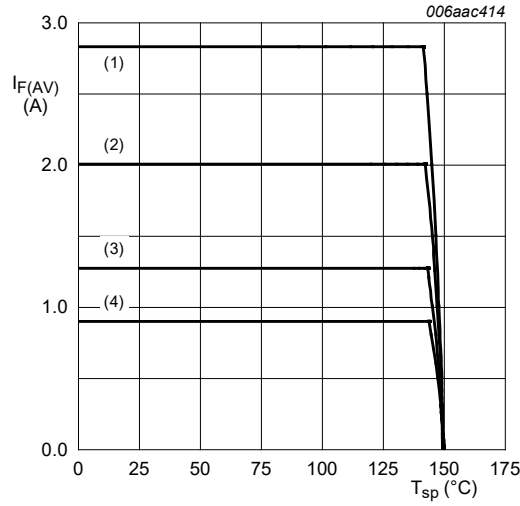
FR4 PCB, mounting pad for cathode  $1\text{ cm}^2$   
 $T_j = 150\text{ }^\circ\text{C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 10. Average forward current as a function of ambient temperature; typical values**



Ceramic PCB,  $\text{Al}_2\text{O}_3$ , standard footprint  
 $T_j = 150\text{ }^\circ\text{C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 11. Average forward current as a function of ambient temperature; typical values**



$T_j = 150$  °C  
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20$  kHz  
 (3)  $\delta = 0.2$ ;  $f = 20$  kHz  
 (4)  $\delta = 0.1$ ;  $f = 20$  kHz

Fig. 12. Average forward current as a function of solder point temperature; typical values

### 11. Test information

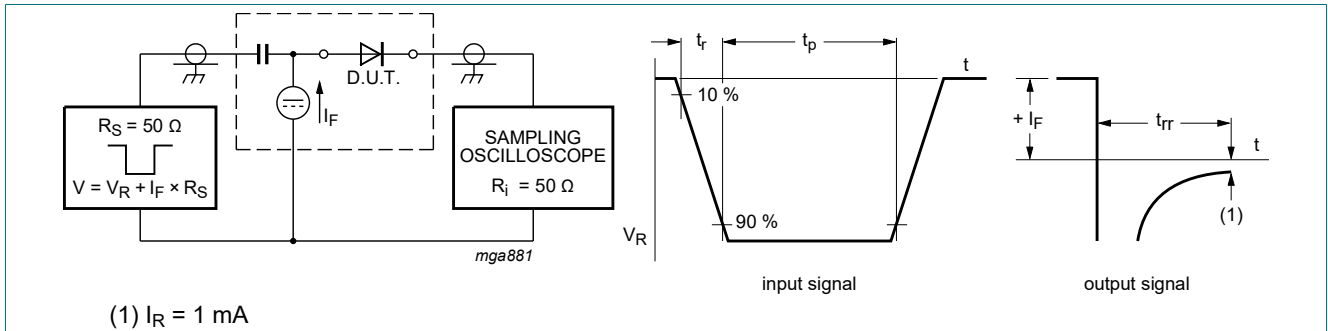


Fig. 13. Reverse recovery time: test circuit and waveforms

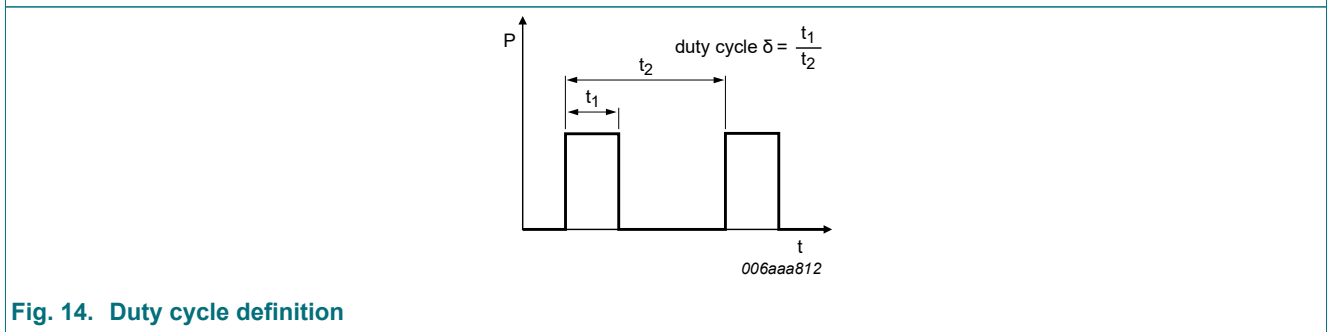


Fig. 14. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC}$$

$$I_{RMS} = I_M \times \sqrt{\delta} \text{ with } I_{RMS} \text{ defined as RMS current}$$

#### Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

### 12. Package outline

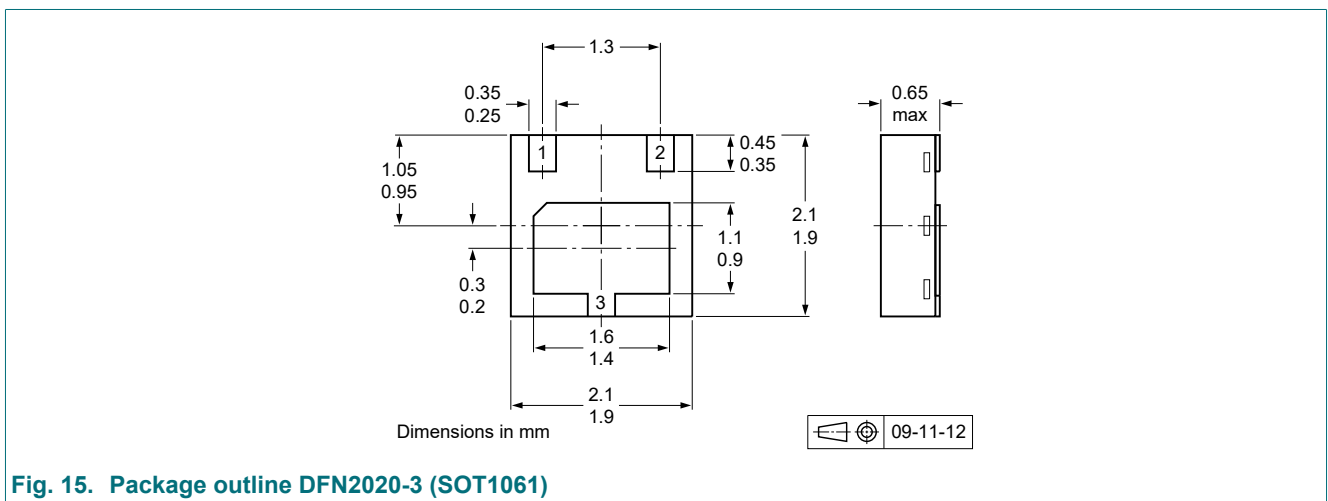
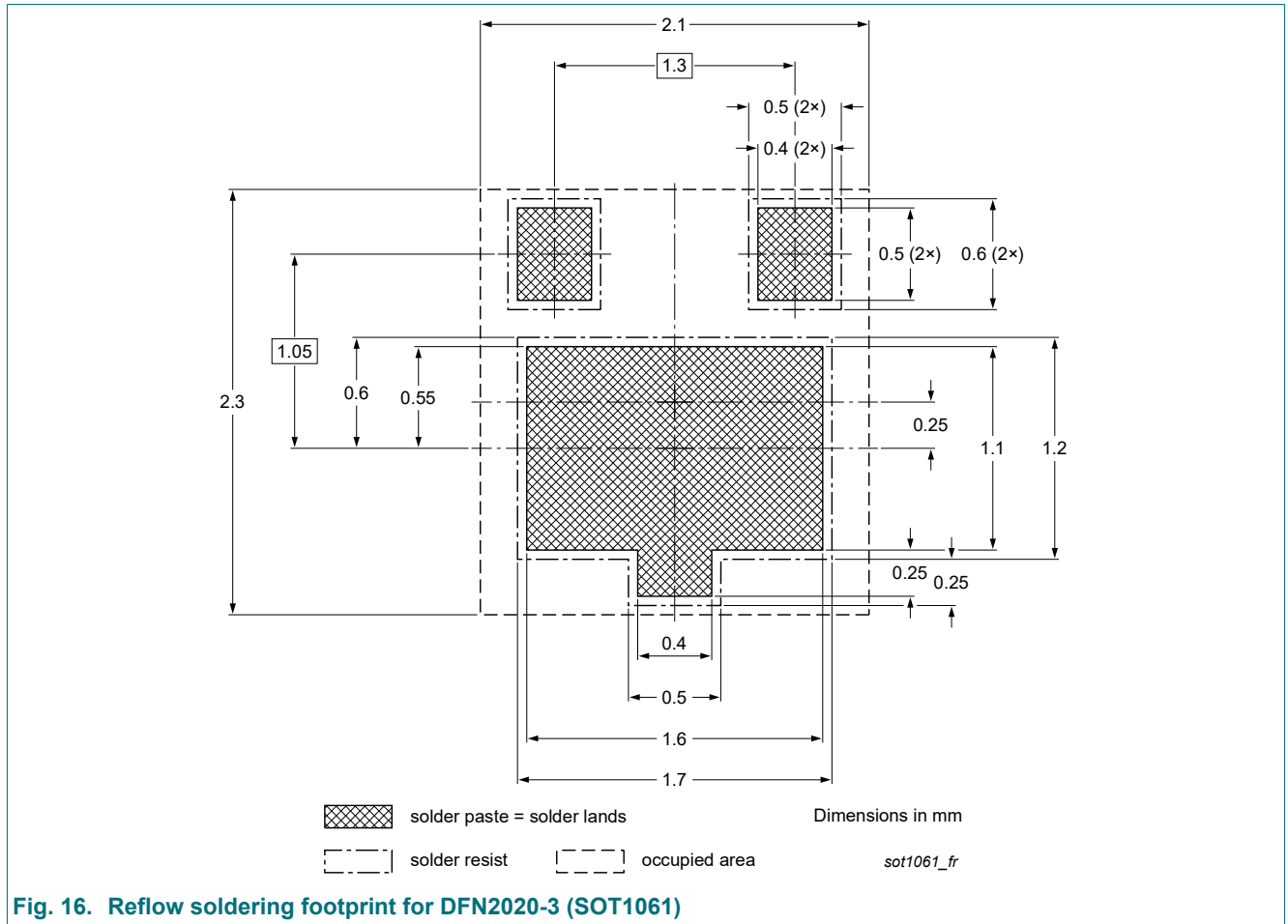


Fig. 15. Package outline DFN2020-3 (SOT1061)



### 13. Soldering



**Fig. 16. Reflow soldering footprint for DFN2020-3 (SOT1061)**

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG2020CPA v.2	20240910	Product data sheet	-	PMEG2020CPA v.1
Modifications:	<ul style="list-style-type: none"><li>• The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia.</li><li>• Legal texts have been adapted to the new company name where appropriate.</li><li>• Section "Packing information" removed.</li></ul>			
PMEG2020CPA v.1	20100805	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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